

Diode

Silicon Carbide Schottky Diode

IDH10G120C5

5th Generation CoolSiC™ 1200 V SiC Schottky Diode

Final Datasheet

Rev. 2.2 2021-03-01

Industrial Power Control



CoolSiC[™] SiC Schottky Diode

Features:

- Revolutionary semiconductor material Silicon Carbide
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant

Benefits

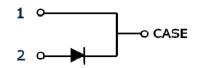
- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size / cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- RelatedLinks: <u>www.infineon.com/sic</u>

Applications

- Solar inverters
- Uninterruptable power supplies
- Motor drives
- Power Factor Correction

Package pin definitions

- Pin 1 and backside cathode
- Pin 2 anode













Key Performance and Package Parameters

Туре	V _{DC}	I F	Q _C	$ all_{ extsf{j,max}}$	Marking	Package
IDH10G120C5	1200V	10A	41nC	175°C	D1012C5	PG-TO220-2-1

1) J-STD20 and JESD22





5th Generation CoolSiC[™] 1200 V SiC Schottky Diode

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Maximum ratings

Parameter	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM}	1200	V	
Continues forward current for $R_{th(j-c,max)}$ $T_C = 155^{\circ}C$, D=1 $T_C = 135^{\circ}C$, D=1 $T_C = 25^{\circ}C$, D=1	IF	10.0 15.2 31.9	А	
Surge non-repetitive forward current, sine halfwave $T_C=25^{\circ}\text{C}$, $t_p=10\text{ms}$ $T_C=150^{\circ}\text{C}$, $t_p=10\text{ms}$	<i>I</i> F,SM	99 84	А	
Non-repetitive peak forward current $T_C = 25^{\circ}C$, $t_p=10 \mu s$	I _{F,max}	711	А	
i²t value $T_C = 25$ °C, $t_p=10$ ms $T_C = 150$ °C, $t_p=10$ ms	∫ i²dt	49 35	A²s	
Diode dv/dt ruggedness $V_R=0960V$	d <i>v</i> /d <i>t</i>	150	V/ns	
Power dissipation $T_C = 25^{\circ}C$	P _{tot}	165	W	
Operating temperature	T _j	-55175	°C	
Storage temperature	T _{stg}	-55150	°C	
Soldering temperature, wavesoldering only allowed at leads, 1.6mm (0.063 in.) from case for 10 s	Tsold	260	°C	
Mounting torque M3 and M4 screws	М	0.7	Nm	

Thermal Resistances

Parameter	Symbol	Conditions		Value		
raiailletei	Symbol		min.	typ.	max.	Unit
Characteristic						
Diode thermal resistance, junction – case	R _{th(j-c)}		-	0.7	0.91	K/W
Thermal resistance, junction – ambient	R _{th(j-a)}	leaded	-	-	62	K/W



Electrical Characteristics

Static Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions min.		Value	Unit	
raiailletei	Syllibol		min.	typ.	max.	Oilit
Static Characteristic						
DC blocking voltage	V _{DC}	<i>T</i> _j = 25°C	1200	-	-	V
Diada forward voltage	1/-	<i>I</i> _F = 10A, <i>T</i> _j =25°C	-	1.5	1.8	\/
Diode forward voltage	V _F	<i>I</i> _F = 10A, <i>T</i> _j =150°C	-	2.0	2.6	V
Deverse current		V _R =1200V, T _j =25°C		4	62	
Reverse current	I _R	<i>V</i> _R =1200V, <i>T</i> _j =150°C		22	320	μA

Dynamic Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions		Value		
- arameter	Syllibol		min.	typ.	max.	Unit
Dynamic Characteristics						
Total capacitive charge		V _R =800V, T _j =150°C				
	Qc	$Q_C = \int_C^{V_R} C(V) dV$	-	41	-	nC
		0				
		V _R =1 V, <i>f</i> =1 MHz	-	525	-	
Total Capacitance	С	<i>V</i> _R =400 V, <i>f</i> =1 MHz	-	37	-	pF
		V _R =800 V, f=1 MHz	-	29	-	



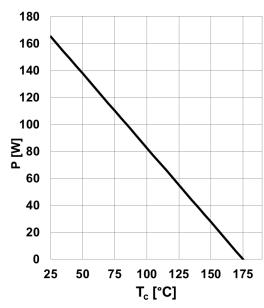


Figure 1. Power dissipation as a function of case temperature, $P_{tot} = f(T_C)$, $R_{th(j-c),max}$

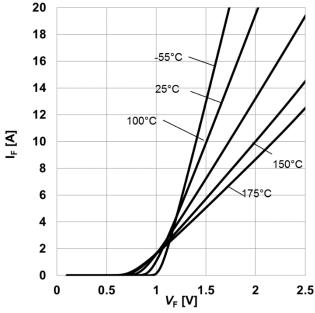


Figure 3. **Typical forward characteristics**, $I_F = f(V_F)$, $t_p = 10 \mu s$, parameter: T_j

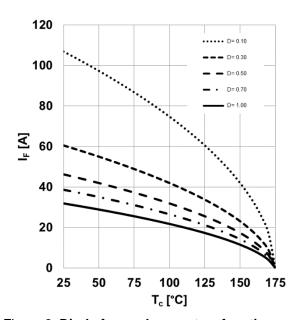


Figure 2. Diode forward current as function of temperature, $T_j \le 175$ °C, $R_{\text{th(j-c),max}}$, parameter D=duty cycle, V_{th} , R_{diff} @ $T_j = 175$ °C

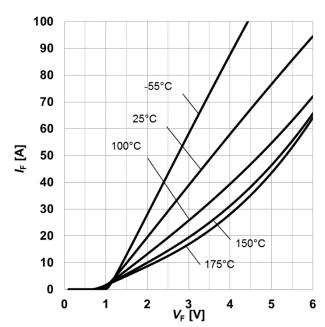


Figure 4. Typical forward characteristics in surge current, $I_F=f(V_F)$, $t_P=10 \mu s$, parameter: T_j



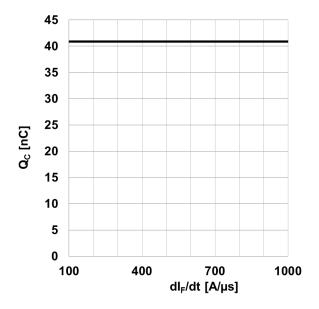


Figure 5. **Typical capacitive charge as function of current slope**¹, $Q_C=f(dI_F/dt)$, $T_j=150^{\circ}C$ 1) Only capacitive charge, guaranteed by design.

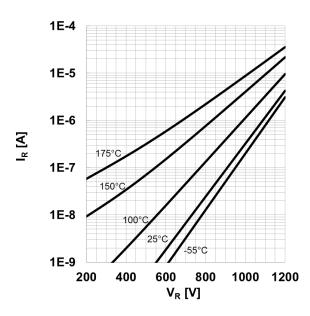


Figure 6. Typical reverse current as function of reverse voltage, $I_R=f(V_R)$, parameter: T_j

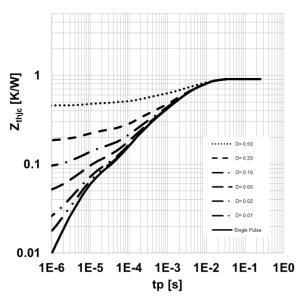


Figure 7. **Max.** transient thermal impedance, $Z_{\text{th,jc}} = f(t_P)$, parameter: $D = t_P/T$

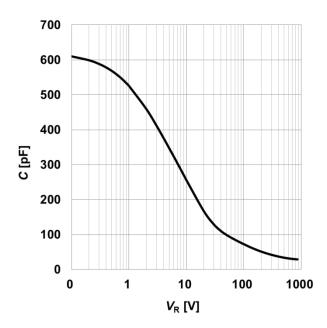


Figure 8. Typical capacitance as function of reverse voltage, $C=f(V_R)$; $T_j=25$ °C; f=1 MHz



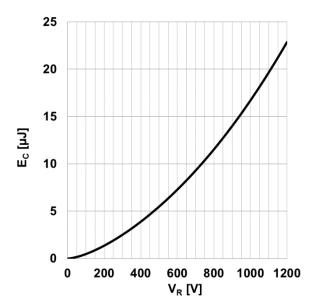
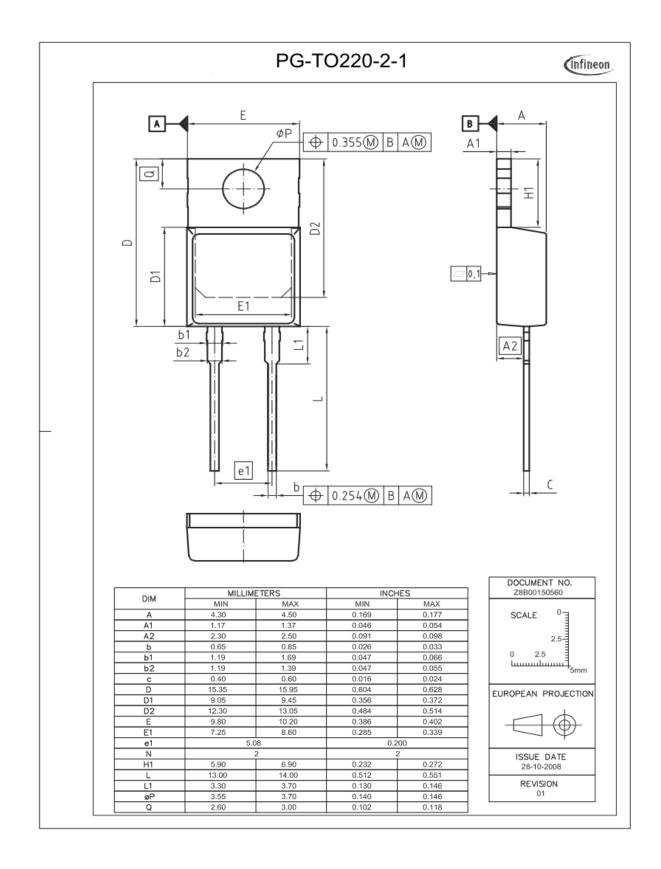


Figure 9. **Typical capacitively stored energy as** function of reverse voltage,

$$E_C = \int_0^{V_R} C(V)VdV$$







Revision History

IDH10G120C5

Revision: 2021-03-01, Rev. 2.2

Previous Revision:

Revision	Date	Subjects (major changes since last version)		
2.0	2015-07-22	Final data sheet		
2.1	2017-07-21	Editorial Changes		
2.2	2021-03-01	Increased dv/dt ruggedness		

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